

What is claimed is:

1. A multilayer printed wiring board having an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor layer being electrically connected through a via hole, characterized in that

a thickness of the conductor layer on said core substrate is larger than a thickness of the conductor layer on the interlayer insulating layer.

10 2. A multilayer printed wiring board having an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor layer being electrically connected through a via hole, characterized in that

if a thickness of the conductor layer on said core substrate is α_1 and a thickness of the conductor layer on the interlayer insulating layer is α_2 , α_1 and α_2 satisfy $\alpha_2 < \alpha_1 \leq 40\alpha_2$.

15 3. The multilayer printed wiring board according to claim 1, characterized in that said α_1 satisfies $2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

20 4. The multilayer printed wiring board according to any one of claims 1 to 3, characterized in that the conductor layer of said core substrate is the conductor layer for a power supply layer or the conductor layer for an earth.

25 5. The multilayer printed wiring board according to any one of claims 1 to 4, characterized in that a capacitor is mounted

on a surface of the multilayer printed wiring board.

6. A multilayer printed wiring board having an interlayer insulating layer and a conductor layer formed on a core substrate, 5 the conductor layer being electrically connected through a via hole, characterized in that

 said core substrate is a multilayer core substrate comprising not less than three layers including a thick conductor layer as an inner layer;

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 the conductor layer as the inner layer and the conductor layer on a surface of said core substrate are the conductor layers for a power supply layer or the conductor layers for an earth.

15 7. A multilayer printed wiring board having an interlayer insulating layer and a conductor layer formed on a core substrate, the conductor layer being electrically connected through a via hole, characterized in that

 said core substrate is a multilayer core substrate comprising not less than three layers including a thick conductor layer as an inner layer;

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 a conductor layer as an inner layer of said core substrate is the conductor layer as a power supply layer or the conductor layer as an earth and that a conductor layer on a surface layer of said core substrate comprises a signal line.

8. A multilayer printed wiring board according to claim 6 or 7, characterized in that

a thickness of the conductor layer on said core substrate is larger than a thickness of the conductor layer on the interlayer insulating layer.

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9. The multilayer printed wiring board according to claim 6 or 7, characterized in that the conductor layer as the inner layer of said core substrate is not less than two conductor layers.

10. 10. The multilayer printed wiring board according to claim 6 or 7, characterized in that said core substrate is constituted so that the conductor layer as said inner layer is formed on each surface of an electrically isolated metallic plate through a resin layer and so that said conductor layer on the surface layer is formed outside of the conductor layer as the inner layer through the resin layer.

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11. The multilayer printed wiring board according to claim 6 or 7, characterized in that said core substrate comprises a thick conductor layer as the inner layer and a thin conductor layer as the conductor layer on the surface layer.

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